

# DS – 11S

## Selective Soldering Dip Tester



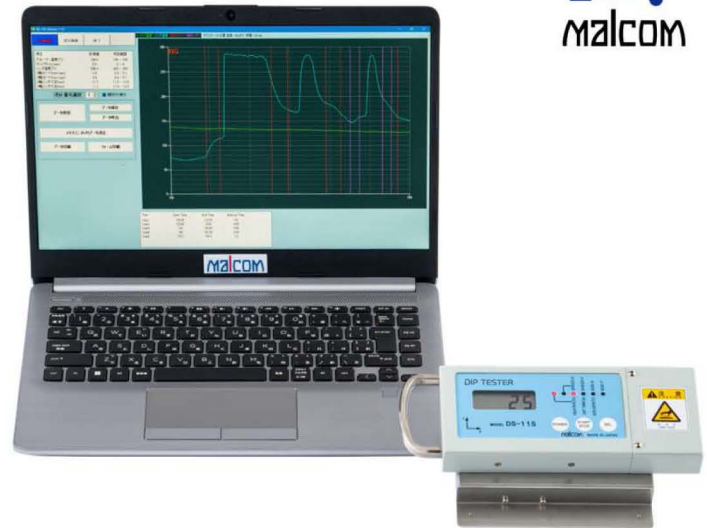
The Dip Tester designed specifically for selective soldering equipment has been upgraded.

Model DS-11S for Selective Soldering Equipment improves process management efficiency by measuring Solder temperature, Soldering time, Temperature rising condition, Moving speed and Solder dimensions a once.

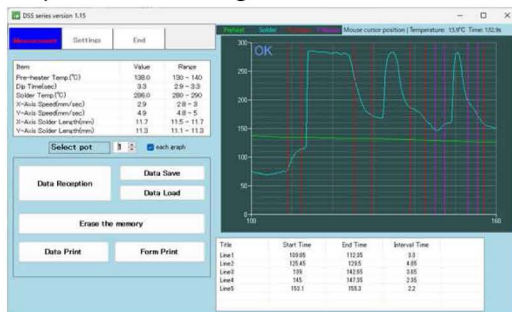
# Special Features for DS-11S



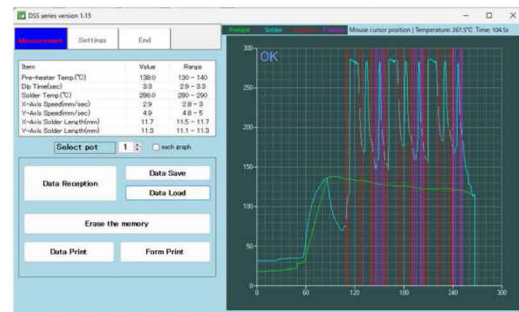
- Preheat and soldering temperatures, XY speed, and soldering dimensions for XY nozzles are automatically determined, enabling easy device condition management.
- Using dedicated software, OK/NG judgment and measurement result management can be performed.
- For devices with multiple nozzles, the condition of up to five nozzles can be individually assessed.
- All results can be checked on the main display without the need for a PC.



Equipped with USB communication and profile measurement functionality, it allows for more advanced measurement of various parameters using dedicated software.



Single measurement example



Triple measurement example

## Measurement Data Specifications

Items	Sensor	Display	Measurement Range	Accuracy
Solder temp.	K-type sheath thermocouple	LCD digital 3-digit	0~330℃	± 1℃
PC board back surface temp.	K-type thermocouple		0~330℃	± 1℃
Dip time	Electrode (2pcs.)		0~10.0sec.	± 0.2sec.
X-Y axis moving speed	Electrode (8pcs.)		0~20mm/sec.	
X-Y axis solder size	Electrode (8pcs.) Calculated from the moving speed & contact time to the electrodes		0~35mm	

## General Specifications

Cold contact point compensation	Compensation with platinum temp. measuring resistor
Ambient temp.	5 minutes max. at 150℃
Battery	AAA batteries x 2pcs.
External connection	USB (type A – type C)
Number of memory	1 data
Sampling time	0.1sec. (fix)
Outer dimensions	140 (W) x 214 (D) x 52 (H) mm
Weight	Approx. 900g (batteries are not included)

\* The above specifications are subject to change without notice.

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